Product Change Notification: BLAS-25TFGQ302

Date:

06-Jun-2025

Product Category:

Memory

Notification Subject:

CCB 7626 Final Notice: Qualification of CuPdAu as a new wire material and QMI519 as a new die attach material for selected 24AA01, 24AA01H, 24AA02, 24AA02H, 24AA04, 24AA04H, 24AA08, 24AA08H, 24AA16, 24AA16H, 24FC01, 24FC02, 24FC04, 24FC04H, 24FC08, 24FC16, 24FC16H, 24LC01B, 24LC01BH, 24LC02B, 24LC02BH, 24LC04B, 24LC04BH, 24LC08B, 24LC08BH, 24LC16B, 24LC16BH, 25AA320A, 25AA640A, 25CS320, 25CS640, 25LC320A, 25LC640A, AT24C01D, AT24C02D, AT24C04D, AT24C08C, AT24C08D, AT24C16C, AT24C16D and AT24C32E device families available in 8L SOIC (.150in) package.

Affected CPNs:

BLAS-25TFGQ302_Affected_CPN_06062025.pdf
BLAS-25TFGQ302_Affected_CPN_06062025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of CuPdAu as a new wire material and QMI519 as a new die attach material for selected 24AA01, 24AA01H, 24AA02, 24AA02H, 24AA04, 24AA04H, 24AA08, 24AA08H, 24AA16, 24AA16H, 24FC01, 24FC02, 24FC04, 24FC04H, 24FC08, 24FC16, 24FC16H, 24LC01B, 24LC01BH, 24LC02B, 24LC02BH, 24LC04B, 24LC04BH, 24LC08B, 24LC08BH, 24LC16B, 24LC16BH, 25AA320A, 25AA640A, 25CS320, 25CS640, 25LC320A, 25LC640A, AT24C01D, AT24C02D, AT24C04D, AT24C08C, AT24C08D, AT24C16C, AT24C16D and AT24C32E device families available in 8L SOIC (.150in) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**

Assembly Site	Microchip Technology Thailand (HQ) (MTAI)		Microchip Technology Thailand (HQ) (MTAI)
Wire Material	Au	CuPdAu	CuPdAu
Die Attach Material	8390A		QMI519
Molding Compound Material	G600V		G600V
Lead-Frame Material	CDA194		CDA194

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability CuPdAu as a new wire material and QMI519 as a new die attach material

Change Implementation Status: In Progress

Estimated First Ship Date: 22 July 2025 (date code: 2530)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	May 2025					>	**July 2025**				
Work Week	18	19	20	21	22		27	28	29	30	31
Qual Report Availability					x						
Final PCN Issue Date					x						
Estimated Implementation Date										x	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: May 30, 2025: Issued final notification
June 06, 2025: Re-issued final notification. Updated to Qualification Report Summary in Qual Report attachment.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_BLAS-25TFGQ302_Qual_Report_.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

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